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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
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10/709,428

05/05/2004

Cheng-Yen Huang

FTCP0035USA

3427

27765

7590

03/27/2006

NORTH AMERICA INTELLECTUAL PROPERTY CORPORATION

P.O. BOX 506

MERRIFIELD, VA 22116

EXAMINER

TRINH, HOA B

ART UNIT

PAPER NUMBER

2814

DATE MAILED: 03/27/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

# Office Action Summary

Application No.

10/709,428

Applicant(s)

HUANG, CHENG-YEN

Examiner

Vikki H. Trinh

Art Unit

2814

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

## Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

## Status

- 1) ☒ Responsive to communication(s) filed on 21 December 2005.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

## Disposition of Claims

- 4) ☒ Claim(s) 11, 19, 33 and 34 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 11, 19, 33 and 34 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

## Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
- Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

## Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some \* c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

## Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)  
Paper No(s)/Mail Date \_\_\_\_\_
- 4) ☐ Interview Summary (PTO-413)  
Paper No(s)/Mail Date. \_\_\_\_\_
- 5) ☐ Notice of Informal Patent Application (PTO-152)
- 6) ☐ Other: \_\_\_\_\_

## DETAILED ACTION

### Acknowledgement

An amendment filed on 12/21/05 has been considered. Claims 11, 19 and 33-34 are pending in this present application.

### *Claim Rejections - 35 USC § 102*

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

2. Claims 11, 19, and 33-34 are rejected under 35 U.S.C. 102(e) as being anticipated by Hatauchi (6,858,920).

As to claim 11, Hatauchi discloses a packaging comprising a package substrate 1 (figure 1A or figure 2) connected to either a high voltage or a low voltage (note that the voltage is the thing that makes the device turns on), a chip 2a or 2b (fig. 1A) mounted on the package substrate and comprises a plurality of bonding option unit that comprises a bonding pad 4a, 4c (fig. 1A); a plurality of first lead frame 5 (fig. 1A); each bonding pad 4a, 4c has corresponding first lead frame 5 (fig. 1A); the first lead frame 5 being connected to either a high voltage or a low voltage (note that the voltage is the thing that makes the device turns on), wherein the voltage level of the first lead frame 5 is

inherently logical opposite of the voltage level of the substrate; wherein each bonding pad 4a, 4c is selectively connected to the package substrate 1 or the first lead frame 5 (fig. 1A) for providing an appropriate voltage to the corresponding bonding unit 4a, 4c (fig. 1A).

As to claim 19, Hatauchi discloses a method of packaging comprising the steps of providing a package substrate 1 (fig. 1A) and connecting it to either a high voltage or a low voltage (note that the voltage is the thing that makes the device turns on), mounting a chip 2a or 2b (fig. 1A) on the package substrate and comprising a plurality of bonding option unit that comprises a bonding pad 4a, 4c (fig. 1A); providing a plurality of first lead frame 5 (fig. 1A); connecting each bonding pad 4a, 4c to the substrate or the corresponding first lead frame 5 (fig. 1A); the first lead frame being connected to either a high voltage or a low voltage (note that the voltage is the thing that makes the device turns on), wherein the voltage level of the first lead frame 5 is inherently logical opposite of the voltage level of the substrate; wherein each bonding pad 4a, 4c is selectively connected to the package substrate 1 or the first lead frame 5 (fig. 1A) for providing an appropriate voltage to the corresponding bonding unit 4a, 4c (fig. 1A).

As to claims 33 and 34, Hatauchi further teaches the device and method of providing a plurality of second lead frames 5 (fig. 2), each bonding pad 4a, 4c of the chip 2a or 2b (fig. 2) having a corresponding second lead frame 5, wherein the second lead frames 5 (fig. 2) are used for inputting or outputting signals to the corresponding bonding pad (note that the pad and lead frames are electrically connected), and each bonding pad 4a, 4c (fig. 2) is selectively connected to the substrate, the corresponding first lead frame

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5 or the corresponding second lead frame 5 (fig. 2). Note that the examiner labels the horizontal lead frame 5 as the first set of lead frames and the vertical lead frames 5 as the second set of lead frames (see figure 2). All of the lead frames 5 are connected to bonding pads 4a, 4c (fig. 2).

### *Response to Arguments*

3. Applicant's arguments with respect to claims 11, 19, and 33-34 have been considered but are moot in view of the new ground(s) of rejection.

### **Conclusion**

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a).

Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire **THREE MONTHS** from the mailing date of this action. In the event a first reply is filed within **TWO MONTHS** of the mailing date of this final action and the advisory action is not mailed until after the end of the **THREE-MONTH** shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than **SIX MONTHS** from the date of this final action.

Any inquiry concerning this communication or earlier communications from the Examiner should be directed to Vikki Trinh whose telephone number is (571) 272-1719. The Examiner can normally be reached from Monday-Friday, 9:00 AM - 5:30 PM Eastern Time. If

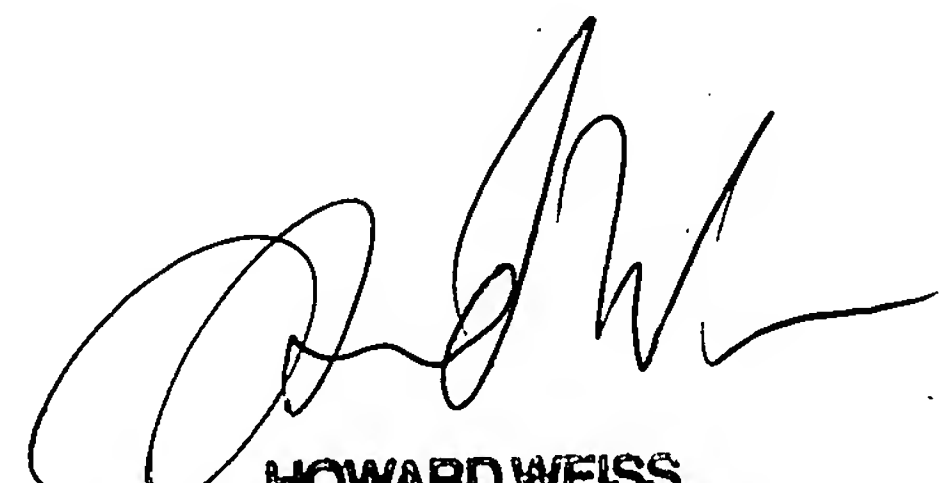
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attempts to reach the examiner by telephone are unsuccessful, the Examiner's supervisor, Mr. Wael Fahmy, can be reached at (571) 272-1705. The office fax number is 703-872-9306.

Any request for information regarding to the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Also, status information for published applications may be obtained from either Private PAIR or Public Pair. In addition, status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. If you have questions pertaining to the Private PAIR system, please contact the Electronic Business Center (EBC) at 866-217-9197 (toll free).

Lastly, paper copies of cited U.S. patents and U.S. patent application publications will cease to be mailed to applicants with Office actions as of June 2004. Paper copies of foreign patents and non-patent literature will continue to be included with office actions. These cited U.S. patents and patent application publications are available for download via the Office's PAIR. As an alternate source, all U.S. patents and patent application publications are available on the USPTO web site ([www.uspto.gov](http://www.uspto.gov)), from the Office of Public Records and from commercial sources. Applicants are referred to the Electronic Business Center (EBC) at <http://www.uspto.gov/ebc/index.html> or 1-866-217-9197 for information on this policy. Requests to restart a period for response due to a missing U.S. patent or patent application publications will not be granted.

Vikki Trinh,  
Patent Examiner  
AU 2814



**HOWARD WEISS**  
**PRIMARY EXAMINER**